



AMPLE Electronic Technology Co., LTD

2025

Investor Meeting

2025/11/13

- The presentation and discussion contain certain forward-looking statements with respect to the results of operation, financial condition and current expectation.
- The forward-looking statements are subject to known and unknown uncertainties and risks that could cause actual results to differ materially from those expressed or implied by such statements. Such risks and uncertainties include but are not limited to the impact of competitive products and pricing, timely project acceptance by our customers, timely introduction of new technologies, ability to ramp new needs into products, financial stability in end markets, and other risks that AMPLE can not control.
- The forward-looking statements in this release reflect the current belief of AMPLE as of the date of this release and AMPLE undertakes no obligation to update these forward-looking statements for events or circumstances that occur subsequent to such date.



- Established: **June 8, 2007**
- Capital: ~ NTD \$ 322 Million
- Main Products :

**Design, Manufacture, and Sales of
conductive materials for advanced
packaging interconnects, thermal
materials, and ceramic components.**

- Location :
**No.32, Dayou 3rd St., Daliao Dist,
Kaohsiung City, Taiwan**

Passive Components

(Capacitor, Incuctor, Resistor)

- Ag paste
- Pd/Ag paste
- Cu paste
- Ni paste

New Materials

- AI

Semiconductor, LED Package:

- Ag paste

Touch Panel:

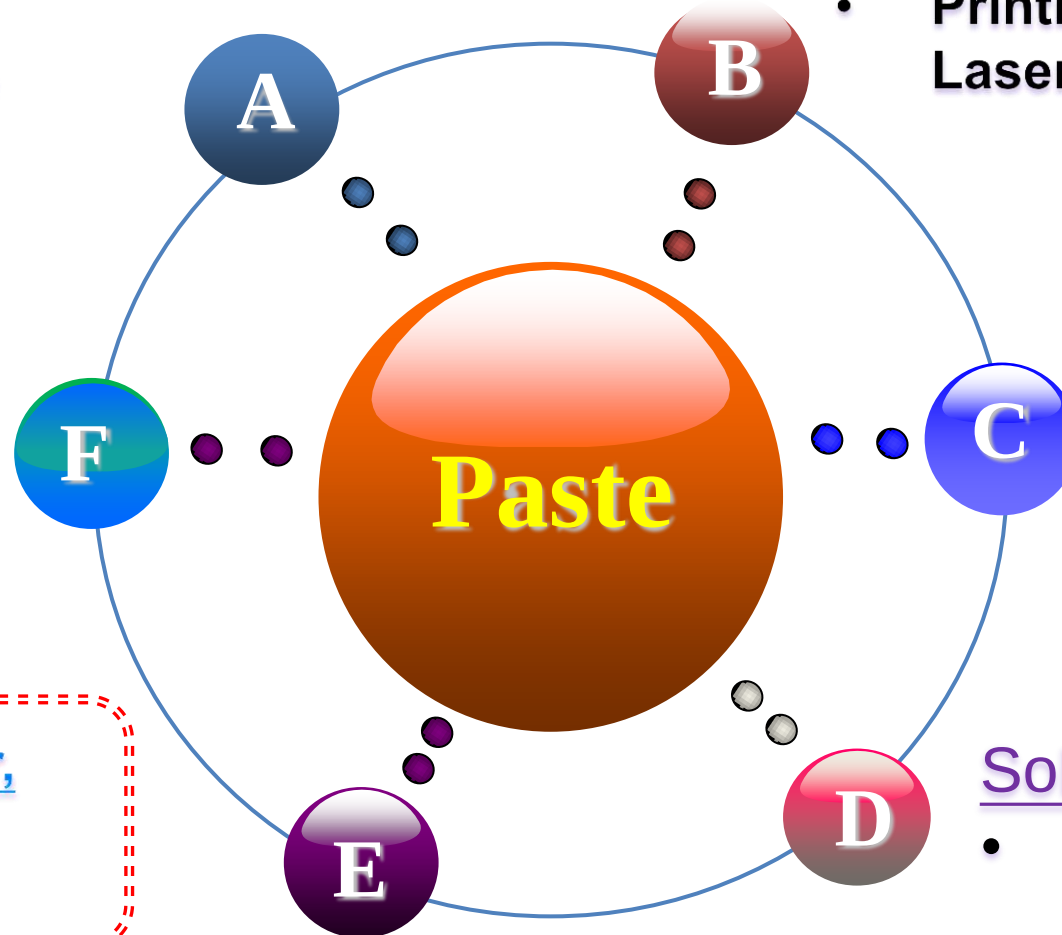
- Printing type
- Laser Etching type

Membrane Switch:

- Ag paste

Solar Cell:

- Rear Ag paste



2025年《天下》兩千大營運績效50強

排名	公司名稱	'22年~'24年 營收成長率 (%)		'22年~'24年 稅後純益成長率 (%)		2024年 股東權益報酬率 (%)		2024年 營收成長率 (%)		2024年 稅後純益成長率 (%)		'22年~'24年 稅後純益總和 (億元)		總分	主要產品
		得分	得分	得分	得分	得分	得分	得分	得分	得分	得分	得分	得分		
1	濟南大自然新材料	91.85	20	158.27	19	50.84	20	42.51	19	61.09	16	147.64	19	113	香菸濾嘴用醋酸纖維絲束
2	華城電機	61.45	19	126.15	19	48.85	20	45.35	19	66.32	17	77.01	18	112	配電及電力變壓器等設備
3	名軒開發	109.63	20	101.97	18	30.75	19	68.14	19	52.47	16	49.94	17	109	住宅或商業大樓興建、租售
4	世芯電子	94.59	20	87.48	18	16.33	11	70.49	19	93.86	19	116.05	19	106	特殊應用積體電路設計製造
4	富宇地產	336.52	20	702.84	20	27.95	18	84.33	20	168.56	20	9.84	8	106	住宅或商業大樓興建、租售
6	台光電子材料	29.02	18	37.41	13	27.29	18	55.89	19	74.53	18	201.39	19	105	銅箔基板、黏合片等
6	新潤興業	91.29	20	72.32	17	25.10	17	149.25	20	117.71	19	17.44	12	105	住宅及大樓興建、租售
8	昇益開發	145.76	20	152.32	19	33.16	19	124.26	20	130.12	19	6.08	6	103	住宅及大樓興建、租售
8	皇普建設	75.59	20	133.62	19	18.29	12	188.16	20	436.78	20	17.79	12	103	住宅或商業大樓興建、租售
40	潤德室內裝修設計工程	37.34	18	47.47	15	25.28	17	31.73	17	51.35	15	4.75	4	86	設計與裝修工程
43	中台資源科技	43.14	19	50.74	15	14.95	9	34.98	18	60.39	16	8.44	8	85	廢棄物資源化處理
43	勤創科技	26.80	17	43.71	14	20.54	14	42.78	19	62.39	17	3.99	4	85	被動元件導電漿
45	力麗科技	52.30	19	29.38	11	22.34	15	99.78	20	35.88	14	5.39	5	84	IoT應用平台暨解決方案
46	肯微科技	24.02	16	36.52	13	9.89	5	32.04	18	78.57	18	21.49	13	83	伺服器電源供應器
46	信鼎技術服務	12.82	11	26.79	10	43.13	20	17.52	14	52.95	16	16.50	12	83	廢棄物資源化處理

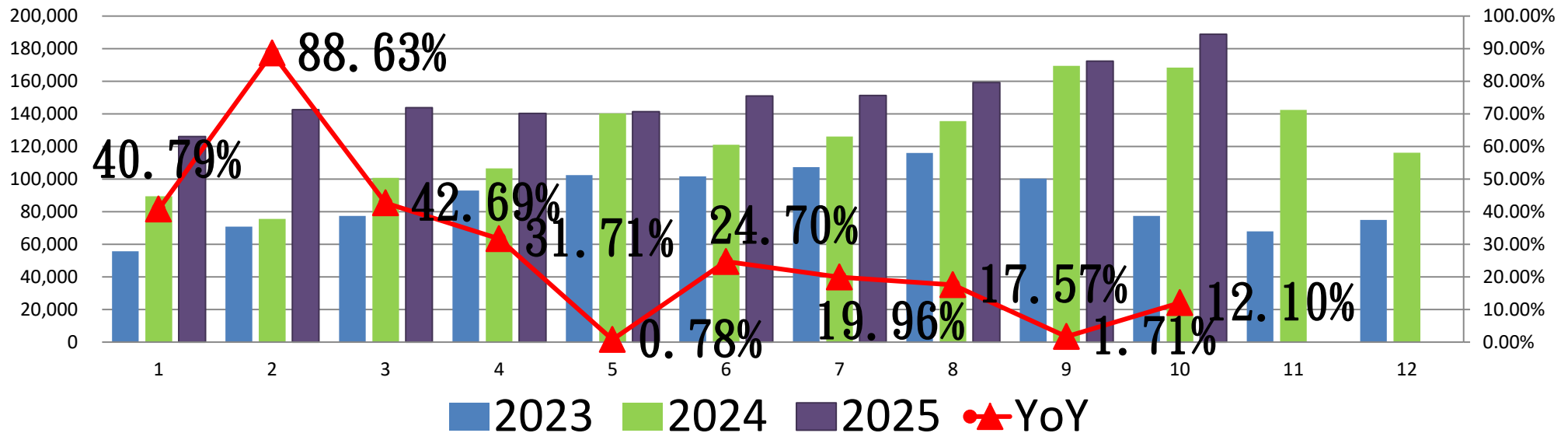


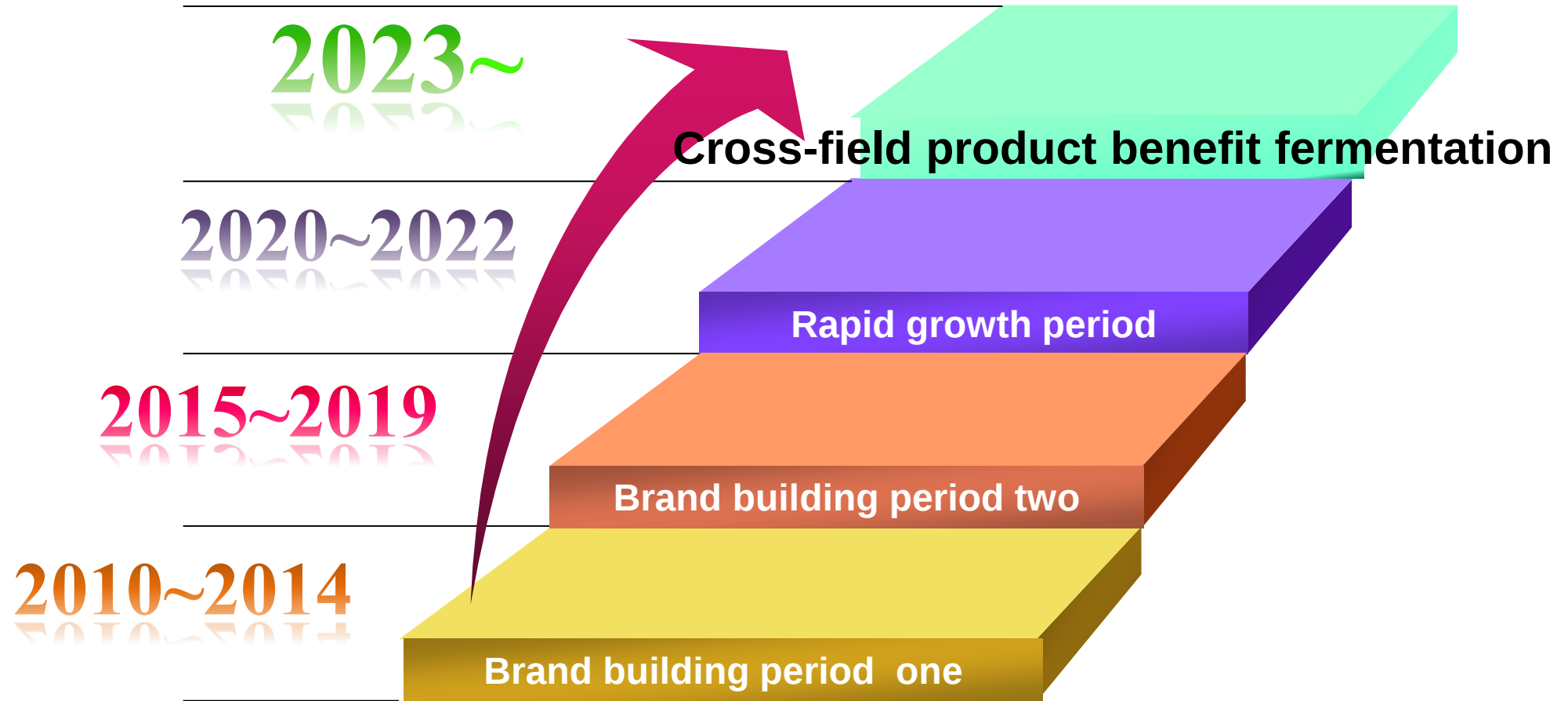
2025年營運績效50強調查方法：將過去3年（2022~2024）每年營收、獲利皆持續成長的製造業與服務業，依長期成長、單年表現及企業規模等6項指標評估企業的營運績效。符合上述條件的企業，分別在每項指標中，依數值高低分成20等份，再依據相對位置給予1到20分。最後，將6項指標的得分加總，以總分排名。名次相同者，依公司名稱筆劃排序。

2025 Monthly Revenue

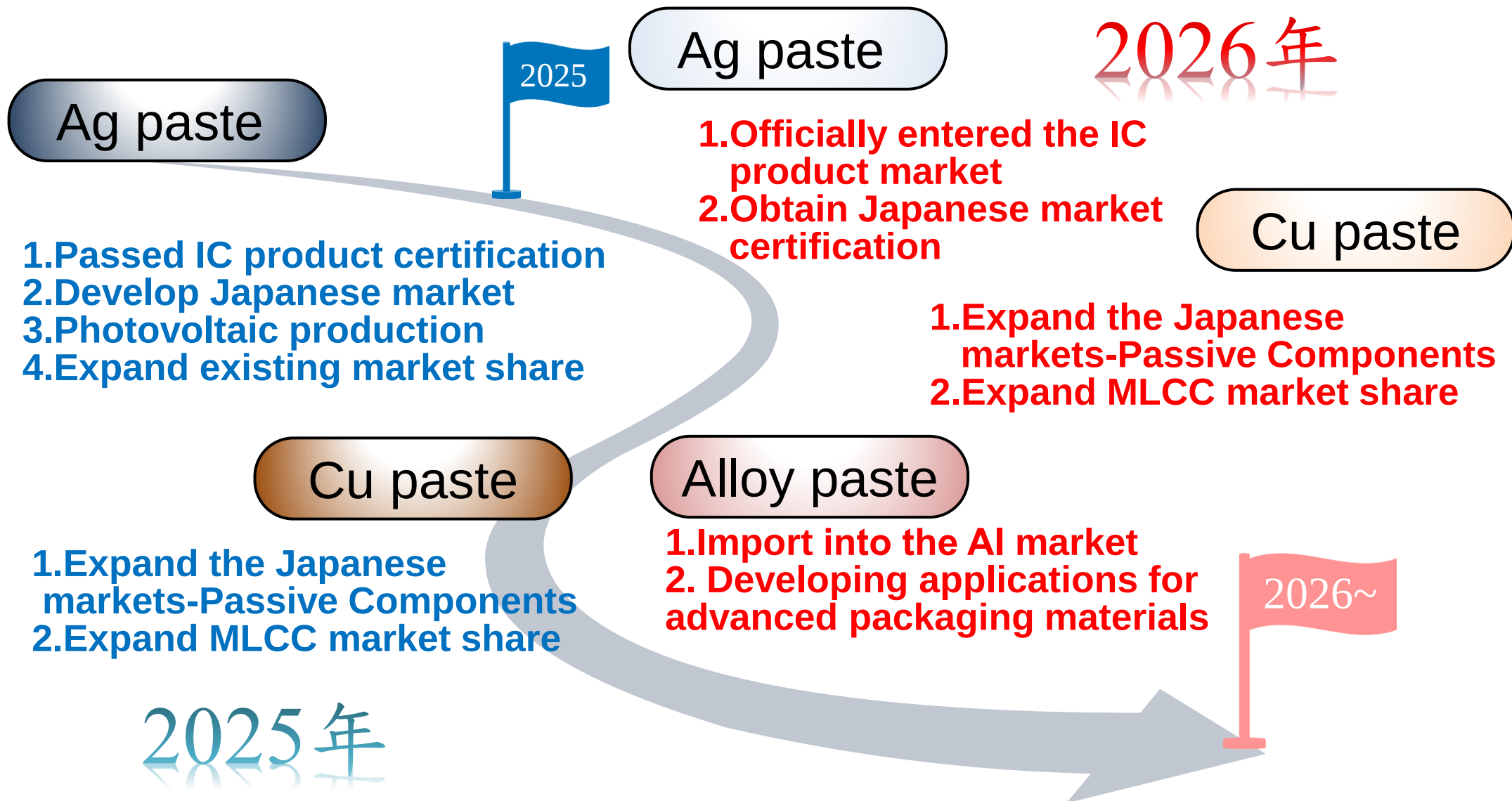
	Jan	Feb	Mar	Apr	May	June	July	Aug	Sep	Oct	Nov	Dec	Accumulated
2021	134,517	140,857	146,066	154,568	155,720	162,519	166,611	165,828	162,539	131,852	112,998	101,094	1,735,167
2022	100,068	80,781	102,422	103,193	100,299	100,052	78,029	54,894	45,927	47,703	53,678	61,045	928,090
2023	55,712	70,767	77,474	92,910	102,508	101,741	107,330	116,087	100,286	77,414	67,862	74,912	1,045,002
2024	89,533	75,599	100,786	106,535	140,287	121,125	126,057	135,482	169,400	168,439	142,406	116,230	1,491,879
2025	126,050	142,604	143,812	140,320	141,377	151,040	151,219	159,285	172,303	188,815			1,516,825
YoY	40.79%	88.63%	42.69%	31.71%	0.78%	24.70%	19.96%	17.57%	1.71%	12.10%			
MoM	8.45%	13.13%	0.85%	-2.43%	0.75%	6.83%	0.12%	5.33%	8.17%	9.58%			

2025 Monthly Revenue





Development Milestones



Expand **ESG** certified products to promote the market to reduce carbon emission pollution and integrate with the world's zero pollution

AMPLE **top R&D team and manufacturing capability**
to create products that meet customer needs

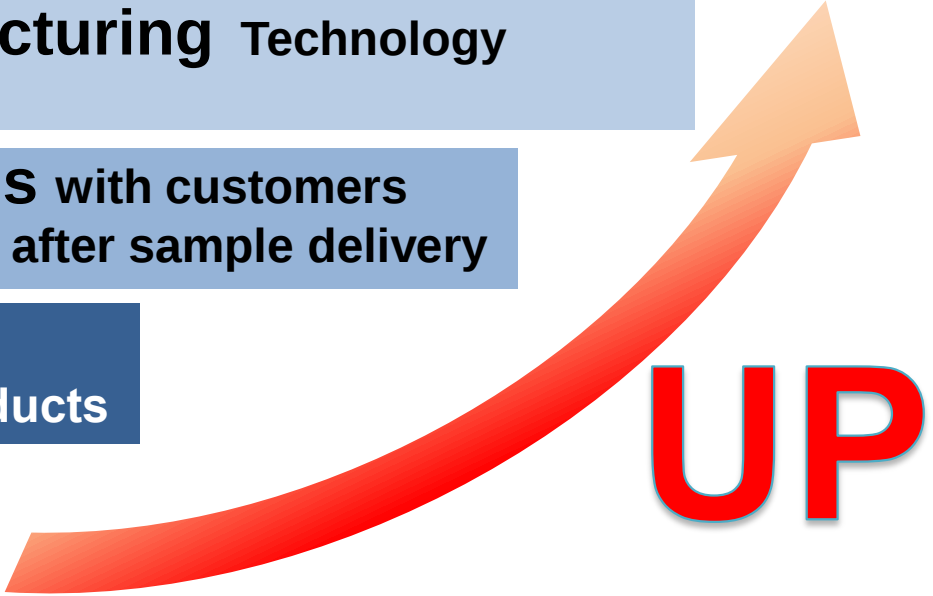
Simulate customer product lines and complete
inspection processes and provide the **Best Quality**

Advanced **Manufacturing Technology**
Capability

Intensive discussions with customers
and **complete testing** after sample delivery

Advanced **R&D capability**
helps design of customer's products

Grasp our customers

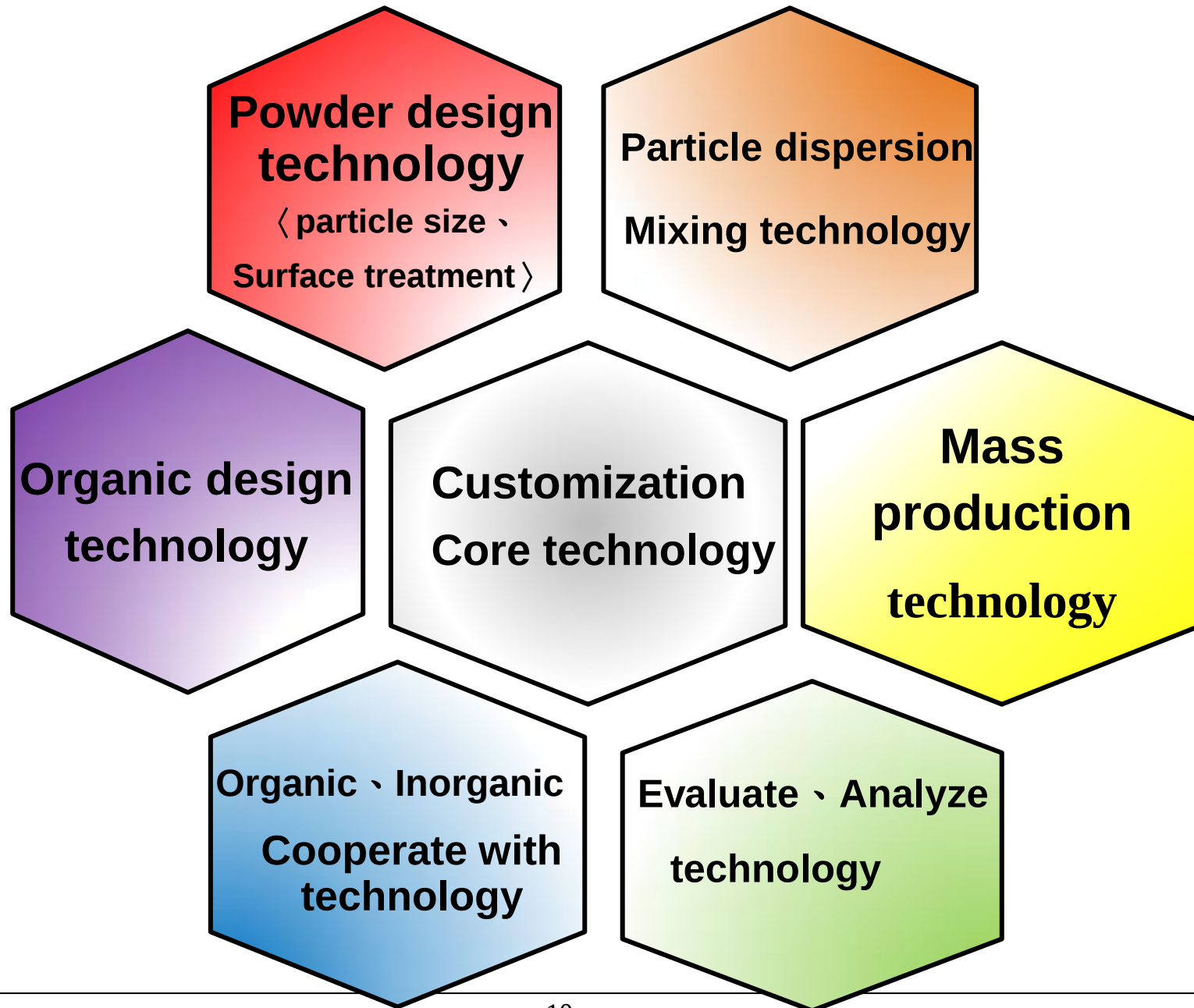


UP

AMPLE is the **leader** in the market.

Our formulation development and product customization capabilities
raise the entry barriers

Core Technology





TIM1-High Thermal Conductivity Material

- TIM1 thermal material is applied in advanced packaging, providing innovative thermal dissipation solutions.

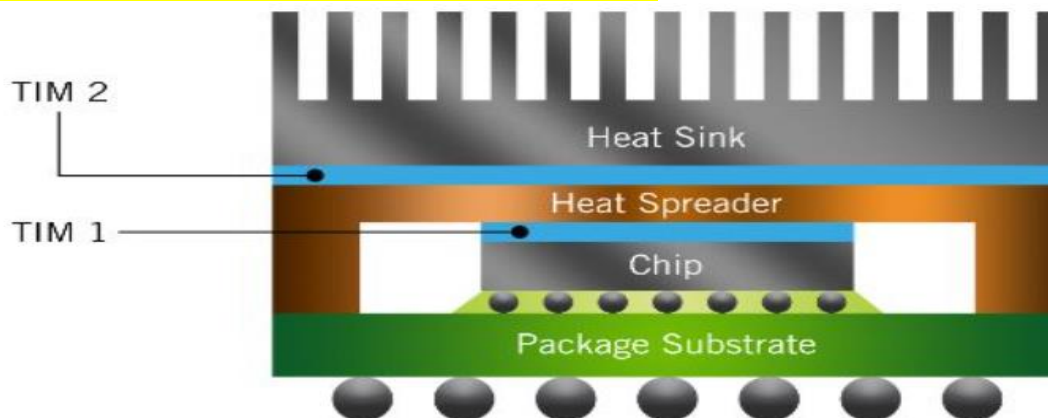
Materials used for TIM1 in the market

	Thermal Conductivity	Issues of the materials
Silicone	8 W/m.K	Low modulus but poor thermal conductivity
graphite	20 W/m.K	Increase adhesive bonding
Indium	80 W/m.K	High thermal conductivity but large modulus

TIM1 material technical specifications
 Thermal conductivity : $> 80 \text{ W/m.K}$
 Modulus: $< 3 \text{ GPa}$
 Application size : $65 \times 65 \text{ mm}$



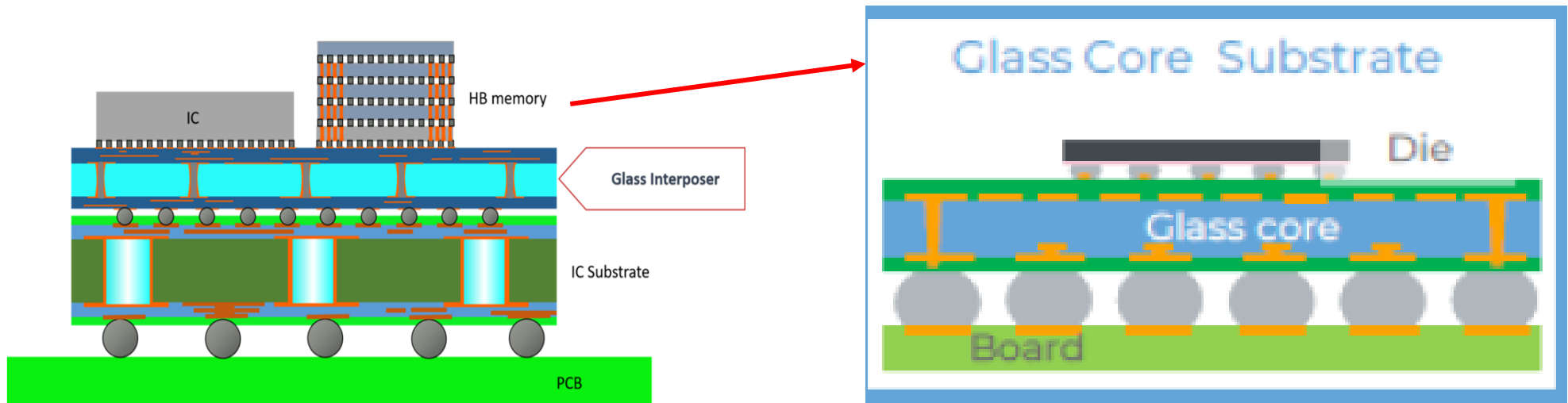
Introducing semi-sintered material for modification
 1.High thermal conductivity
 2.Low modulus



TGV(Through Glass Via)

The original silicon in the interposer is replaced with **glass**, and TGV technology forms conductive channels on the **glass substrate** to connect multi-layer circuits.

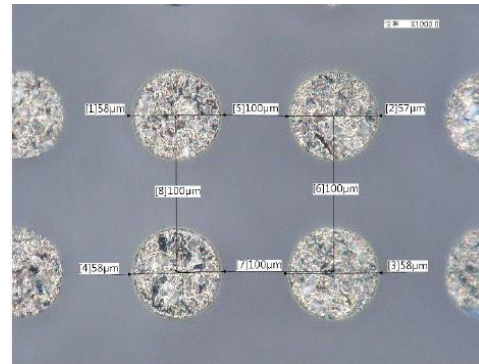
The advantages of using glass substrate include **low cost, good dielectric properties, transparency, high rigidity, CTE similar to silicon.**



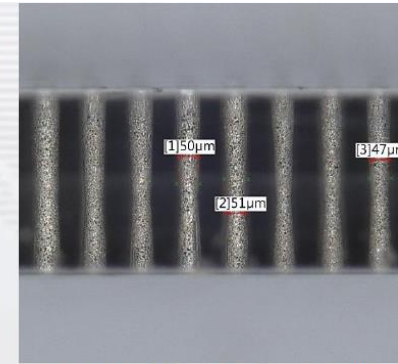
Application category (TGV-performance)

Diameter : 60 μm
Aspect ratio : 1 : 8.3

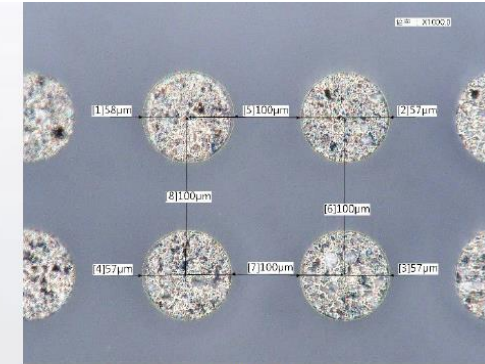
- **Hole filling& glass adhesion:Pass**



Via $\Phi 60\mu\text{m}$ & filled Alloy Cu (Top)



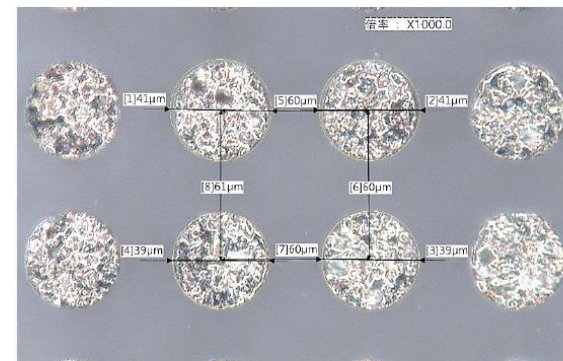
Via $\Phi 60\mu\text{m}$ & filled Alloy Cu (X-section)



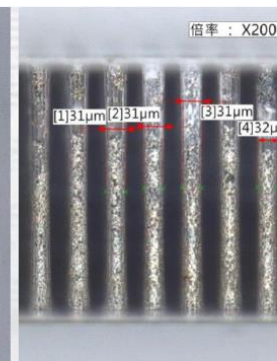
Via $\Phi 60\mu\text{m}$ & filled Alloy Cu (Bottom)

Diameter : 40 μm
Aspect ratio : 1 : 12.5

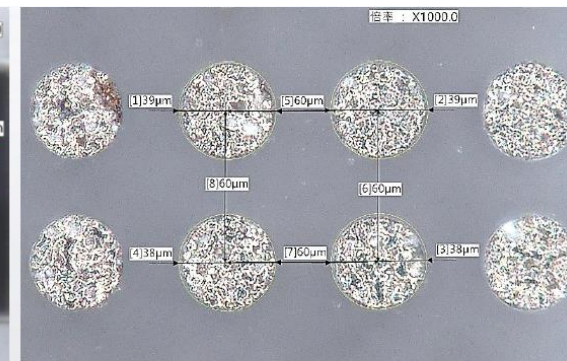
- **Hole filling& glass adhesion:Pass**



Via $\Phi 40\mu\text{m}$ & filled Alloy Cu (Top)



Via $\Phi 40\mu\text{m}$ & filled Alloy Cu (X-section)



Via $\Phi 40\mu\text{m}$ & filled Alloy Cu (Bottom)

Application category (TGV-performance)

Glass thickness	Diameter (Avg.)	Middle diameter (Avg.)	Aspect ratio	Result
470 um	30 um	18 um	1 : 15.7	Hole filling: Pass

TOP



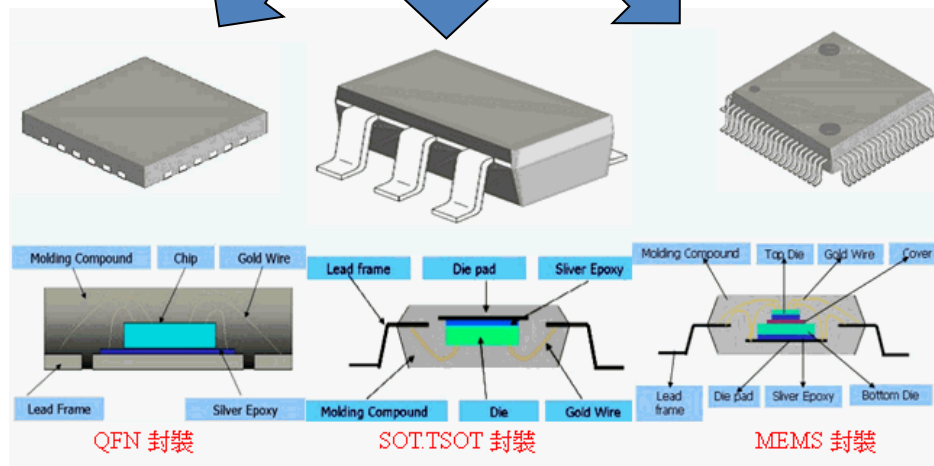
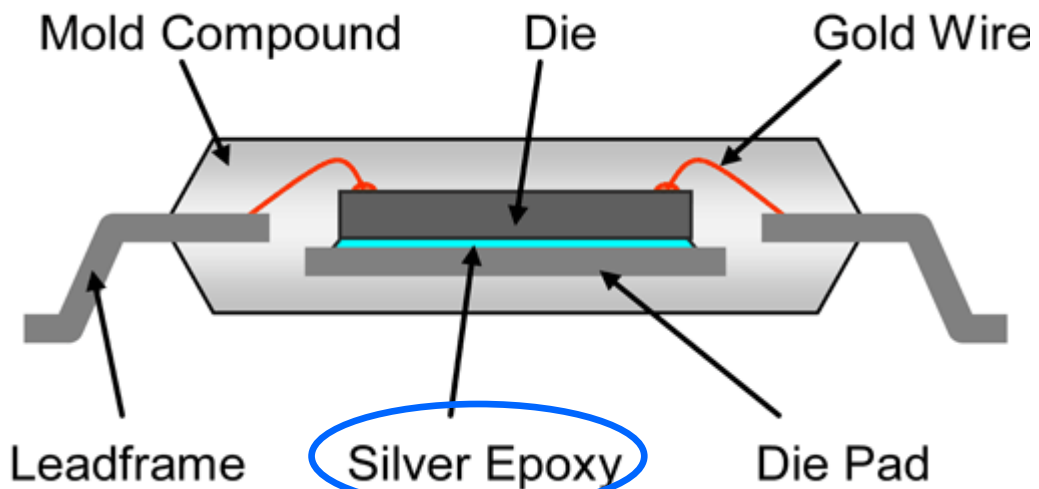
30 degrees laterally



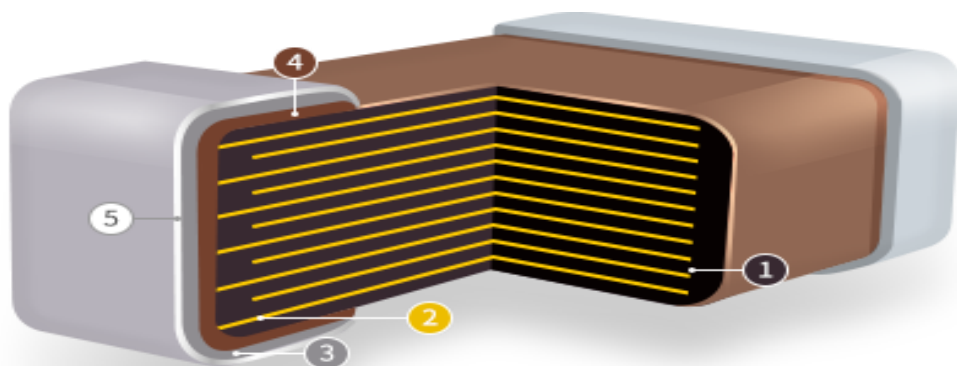
	TGV Conductive Filler Paste
Advantages	◆ Excellent glass adhesion ◆ Low void ratio ◆ No CMP process ◆ High aspect ratio (> 1 : 12) ◆ Low CTE ◆ High thermal conductivity ◆ Excellent volume resistance(5.0E-5 ~ 6.0E-6) ◆ Customization (Viscosity / Volume resistivity / TGV Diameter)



導線架 Die Bonding



MLCC Capacitor



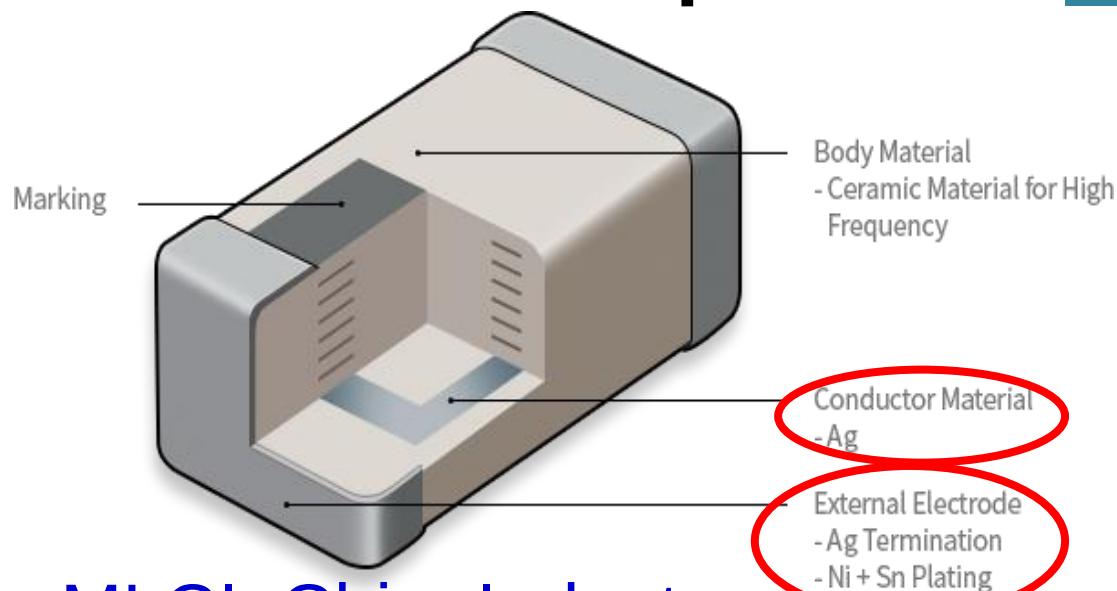
- ① Ceramic body
- ② Electrode(Ni/Cu*)
- ③ Plating(Ni)
- ④ Termination(Cu or Cu+Metal Epoxy)
- ⑤ Plating(Sn)

* Internal Cu electrode is only applied to limited products.

Chip Resistor



MLCI Chip Inductor



Ag vs Cu 金屬價格

KITCO®				
星期二 11-11月-2025 17:33				
Market is Open				
▼ 貴金屬 美國 美元 每 千克				
更新於		買盤	賣盤	變動
17:29	黃金	133200.55	133264.84	903.44
17:29	白銀	1633.58	1637.44	12.22
17:29	鉑金	51312.59	51634.10	643.01
17:29	鈀金	45879.12	47165.15	964.52
07:00	銻	251579.59	269262.50	0.00
▼ 基金屬 每 千克				
更新於		買盤	賣盤	變動
17:25	銅	10.7777	10.7799	-0.0474
▼ 原油*				
更新於		價格		變動

Statements of Comprehensive Income— Quarterly

(Unit: NT Thousand)								3Q2025	
	2021	2022	2023	2024	3Q2025	2Q2025	1Q2025	QoQ	YoY
Net revenue	1,734,567	928,090	1,045,002	1,491,879	482,808	432,736	412,467	12%	12%
Gross profit	351,754	194,267	224,069	326,055	105,556	81,537	95,735	29%	25%
Gross margin(%)	20%	21%	21%	22%	22%	19%	23%	16%	9%
Operating expenses	(107,357)	(89,559)	(95,247)	(104,018)	(29,492)	(23,671)	(28,497)	25%	17%
Operating expenses rate(%)	-6%	-9%	-9%	-7%	-6%	-6%	-7%	0%	0%
Operating income	244,397	104,708	128,822	222,037	76,064	57,866	67,238	31%	28%
Operating margin(%)	14%	12%	12%	15%	16%	13%	16%	23%	14%
Net foreign exchange gain	7,266	12,872	4,808	19,391	11,700	(35,751)	5,262	-133%	-222%
Non-operating incomes and expenses	(3,088)	(1,163)	9,537	(3,633)	(456)	(1,177)	2,142	-61%	-86%
Income before income tax	248,575	116,417	143,167	237,795	87,308	20,938	74,642	317%	87%
Income tax expense	(47,450)	(24,059)	(26,443)	(48,028)	(17,024)	(5,999)	(13,965)	184%	79%
Net income	201,125	92,358	116,724	189,767	70,284	14,939	60,677	370%	89%
Net margin(%)	12%	10%	11%	13%	15%	4%	15%	275%	67%
EPS(NT\$)	6.70	3.08	3.90	6.30	2.22	0.50	2.01	344%	90%
Depreciation	21,097	24,873	23,682	23,271	5,724	5,567	5,553		
CAPEX	24,937	12,419	13,020	12,489	4,892	2,586	2,232		

Balance Sheets

(Unit: NT Thousand)	2025/9/30	2024/12/31	2024/9/30
Cash and cash equivalents	207,509	90,968	98,048
Accounts receivable, net	690,481	665,654	602,283
Inventories	312,180	358,060	290,953
Other current assets	17,143	48,386	71,985
Total current assets	1,227,313	1,163,068	1,063,269
Property, plant and equipment	183,354	190,953	195,873
Other non-current assets	183,920	152,985	164,885
Total non-current assets	367,274	343,938	360,758
Total assets	1,594,587	1,507,006	1,424,027
Current liabilities	627,380	580,865	547,149
Non-Current liabilities	812	1,249	304
Total liabilities	628,192	582,114	547,453
Common stocks	322,183	301,127	321,127
Other equity interest	644,212	623,765	555,447
Total equity	966,395	924,892	876,574
Book value per share(NT\$)	30.00	30.71	27.30
Key Indices			
Current ratio	196%	200%	194%
Debt ratio	39%	38%	38%

Year	2020	2021	2022	2023	2024
EPS (NT\$)	4.74	6.70	3.08	3.90	6.30
Dividends (NT\$)	3.20	4.50	2.20	2.70	4.20
Dividend Payout Ratio(%)	67.51%	67.16%	71.43%	69.23%	66.67%

Distributed dividends for 12 consecutive years!

凱
歌長奏盛名揚

世界級導電漿料供應商

勤
奮開拓質優良